











#### **SN54LV86A, SN74LV86A**

SCLS392G -APRIL 1998-REVISED FEBRUARY 2015

# SNx4LV86A Quadruple 2-Input Exclusive-OR Gates

#### **Features**

- 2-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 8 ns at 5 V
- Typical V<sub>OLP</sub> (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot) >2.3 V at  $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Support Mixed-Mode Voltage Operation on All
- Latch-Up Performance Exceeds 250 mA per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

# **Applications**

- **EPOS**
- Programmable Logic Controller (PLC)
- DCS and PAC: Analog Input Module
- Medical Meters: Portable
- Server Motherboard
- Printer

## 3 Description

The 'LV86A devices are quadruple 2-input exclusive-OR gates designed for 2-V to 5.5-V V<sub>CC</sub> operation.

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)		
	VQFN (14)	3.50 mm × 3.50 mm		
	SOIC (14)	8.65 mm × 3.91 mm		
LV86A	SOP (14)	10.30 mm × 5.30 mm		
	SSOP (14)	6.20 mm × 5.30 mm		
	TSSOP (14)	5.00 mm × 4.40 mm		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

# Simplified Schematic



These are five equivalent exclusive-OR symbols valid for an 'LV86A gate in positive logic; negation can be shown at any two ports. See Functional Block Diagram for more information.



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# 5 Revision History

# Changes from Revision F (April 2005) to Revision G

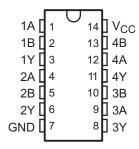
Page

•	Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation	
	section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and	
	Mechanical, Packaging, and Orderable Information section	1
	Updated operating free-air temperature maximum from 85°C to 125°C for SN74I V86A	5

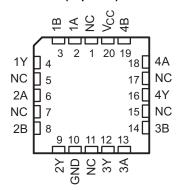


# 6 Pin Configuration and Functions

SN54LV86A: J or W Package SN74LV86A: D, DB, DGV, NS, or PW Package (Top View)



# SN54LV86A: FK Package (Top View)



B. NC - No internal connection

### **Pin Functions**

PIN	I/O	DESCRIPTION
1	1A	A input 1
2	1B	B input 1
3	1Y	Output 1
4	2A	A input 2
5	2B	B input 2
6	2Y	Output 2
7	GND	ground
8	3Y	Output 3
9	3A	A input 3
10	3B	B input 3
11	4Y	Output 4
12	4A	A input 4
13	4B	B input 4
14	V <sub>CC</sub>	Power pin

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# 7 Specifications

## 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	-0.5	7	V
VI	Input voltage <sup>(2)</sup>	-0.5	7	V
Vo	Voltage applied to any output in the high-impedance or power-off state (2)	-0.5	7	V
Vo	Output voltage (2)(3)	-0.5	V <sub>CC</sub> + 0.5 V	V
I <sub>IK</sub>	Input clamp current, V <sub>I</sub> < 0		-20	mA
I <sub>OK</sub>	Output clamp current, V <sub>O</sub> < 0		-50	mA
Io	Continuous output current, $V_0 = 0$ to $V_{CC}$	-25	25	mA
	Continuous current through V <sub>CC</sub> or GND	-50	50	mA
T <sub>stg</sub>	Storage temperature	-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 7.2 ESD Ratings

			VALUE	UNIT
\/	() Licotrodiatio	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	2000	
V(ESD)	discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	1000	V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

<sup>(2)</sup> The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> This value is limited to 5.5-V maximum.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



# 7.3 Recommended Operating Conditions

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
. ,	LPak Javal Sanat valta na	V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7		V
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 2 V		0.5	
. /	Low lovel input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		$V_{CC} \times 0.3$	V
		V <sub>CC</sub> = 4.5 V to 5.5 V		$V_{CC} \times 0.3$	
V <sub>I</sub>	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
-0	High level autout average	V <sub>CC</sub> = 2 V		<b>-</b> 50	μΑ
ı		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2	mA
ОН	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-6	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12	
		$V_{CC} = 2 V$		50	μΑ
ı	Low-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2	
OL	Low-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12	
		V <sub>CC</sub> = 2.3 V to 2.7 V		200	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3 V to 3.6 V		100	ns/V
		V <sub>CC</sub> = 4.5 V to 5.5 V		20	
T <sub>A</sub>	Operating free-air temperature		-55	125	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, SCBA004.

#### 7.4 Thermal Information

	THERMAL METRIC <sup>(1)</sup>		DB	DGV	NS	PW	UNIT	
	THERMAL METRIC		14 PINS					
$R_{\theta JA}$	Junction-to-ambient thermal resistance (2)	90.6	107.1	129.0	90.7	122.6		
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	50.9	59.6	52.1	48.3	51.4		
$R_{\theta JB}$	Junction-to-board thermal resistance	44.8	54.4	62.0	49.4	64.4	°C/W	
ΨЈТ	Junction-to-top characterization parameter	14.7	20.5	6.5	14.6	6.7		
ΨЈВ	Junction-to-board characterization parameter	44.5	53.8	61.3	49.1	63.8		

For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

Product Folder Links: SN54LV86A SN74LV86A

The package thermal impedance is calculated in accordance with JESD 51-7.



#### 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	SN	SN54LV86A			SN74LV86A -40°C to 125°C			
			MIN	TYP	MAX	MIN	TYP	MAX		
	$I_{OH} = -50 \mu A$	2 to 5.5 V	$V_{CC} - 0.1$			V <sub>CC</sub> - 0.1				
M	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V	
V <sub>OH</sub>	$I_{OH} = -6 \text{ mA}$	3 V	2.48			2.48			V	
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			3.8				
	$I_{OL} = 50 \mu A$	2 to 5.5 V			0.1			0.1		
M	$I_{OL} = 2 \text{ mA}$	2.3 V			0.4			0.4	V	
VOL	I <sub>OL</sub> = 6 mA	3 V			0.44			0.44		
$V_{OL}$ $I_{OL} = 2 \text{ mA}$ $2.3 \text{ V}$		0.55			0.55					
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±1			±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20			20	μΑ	
I <sub>off</sub>	$V_{I}$ or $V_{O} = 0$ to 5.5 V	0			5			5	μΑ	
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V		1.4			1.4		pF	

# 7.6 Switching Characteristics, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

DADAMETED	FROM (INPUT)	TO (OUTPUT)	LOAD	Т	<sub>A</sub> = 25°C		MIN	MAY	UNIT
PARAMETER	PROW (INPUT)	10 (001701)	CAPACITANCE	MIN	TYP	MAX	IVIIN	WAX	UNII
	A or D		C <sub>L</sub> = 15 pF		7.9 <sup>(1)</sup>	17.6 <sup>(1)</sup>	1 <sup>(2)</sup>	21 <sup>(2)</sup>	
τ <sub>pd</sub>	A or B	Y Y	C <sub>L</sub> = 50 pF		10.5	22.6	1	26.5	ns

<sup>(1)</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.7 Switching Characteristics, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

DADAMETED	EDOM (INDUT)	TO (OUTPUT)	LOAD	Т	<sub>A</sub> = 25°C		MINI	MAV	LINIT
PARAMETER	FROM (INPUT)	TO (OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN M	MAX	UNIT
	A or D	V	C <sub>L</sub> = 15 pF		5.5 <sup>(1)</sup>	11 <sup>(1)</sup>	1 <sup>(2)</sup>	13 <sup>(2)</sup>	
T <sub>pd</sub>	A or B	Y	C <sub>L</sub> = 50 pF		7.4	14.5	1	16.5	ns

<sup>(1)</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.8 Switching Characteristics, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

	DADAMETED	FROM (INPUT)	TO (OUTPUT)	LOAD	T	<sub>A</sub> = 25°C		MIN	MAY	UNIT
PARAMETER	PROM (INPUT)	TO (OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIN	IVIAA	UNII	
	•	A or B	V	C <sub>L</sub> = 15 pF		3.7 <sup>(1)</sup>	6.8 <sup>(1)</sup>	1 (2)	8 <sup>(2)</sup>	200
	<sup>L</sup> pd	AUIB	1	C <sub>L</sub> = 50 pF		5.3	8.8	1	10	ns

Product Folder Links: SN54LV86A SN74LV86A

<sup>(2)</sup> This note applies to SN54LV86A only: On products compliant to MIL-PRF-38535, this parameter is not production tested.

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<sup>(1)</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

<sup>(2)</sup> This note applies to SN54LV86A only: On products compliant to MIL-PRF-38535, this parameter is not production tested.



## 7.9 Noise Characteristics for SN74LV86A

 $V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C (see}^{(1)})$ 

	PARAMETER	MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V <sub>OL</sub>		0.2	0.8	
$V_{OL(V)}$	Quiet output, minimum dynamic V <sub>OL</sub>		-0.1	-0.8	
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		3.1		V
V <sub>IH(D)</sub>	High-level dynamic input voltage	2.31			
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.99	

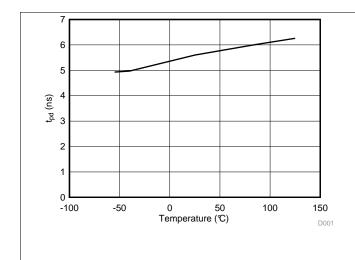
<sup>(1)</sup> Characteristics are for surface-mount packages only.

# 7.10 Operating Characteristics

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	Devian dissination consistence	C 50 = 5 40 MHz	3.3 V	8.4	
	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	5 V	8.8	p⊦	

# 7.11 Typical Characteristics



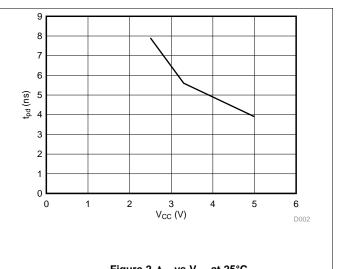
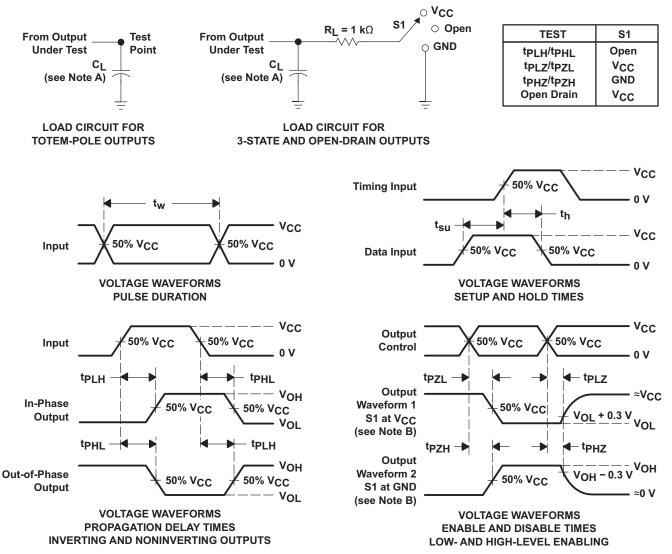


Figure 1.  $t_{pd}$  vs Temperature at 3.3 V

Figure 2. t<sub>pd</sub> vs V<sub>CC</sub> at 25°C



#### 8 Parameter Measurement Information



- C<sub>L</sub> includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq$  3 ns,  $t_f \leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PHL</sub> and t<sub>PLH</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

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# 9 Detailed Description

#### 9.1 Overview

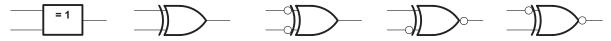
The 'LV86A devices are quadruple 2-input exclusive-OR gates designed for 2-V to 5.5-V  $V_{CC}$  operation.

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

### 9.2 Functional Block Diagram

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



A. These are five equivalent exclusive-OR symbols valid for an 'LV86A gate in positive logic; negation can be shown at any two ports.

Figure 4. Exclusive OR

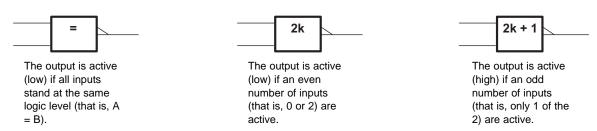


Figure 5. Logic-Identity Element Figure 6. Eve

Figure 6. Even-Parity Element

Figure 7. Odd-Parity Element

## 9.3 Feature Description

- Wide operating voltage range, operates from 2 to 5.5 V
- · Allows down voltage translation, inputs accept voltages to 5.5 V

#### 9.4 Device Functional Modes

Table 1. Function Table (Each Gate)

INP	OUTPUT	
Α	В	Y
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

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# 10 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 10.1 Application Information

The SN74LV86A is a low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs can accept voltages to 5.5~V at any valid  $V_{CC}$  making it Ideal for down translation.

## 10.2 Typical Application

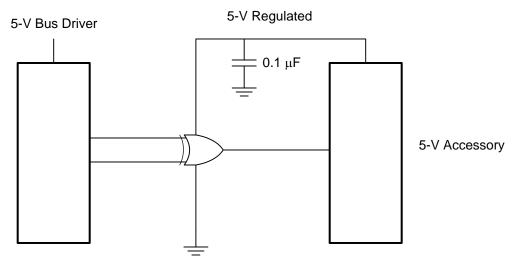


Figure 8. Typical Application Schematic

#### 10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

#### 10.2.2 Detailed Design Procedure

- 1. Recommended Input conditions
  - Rise time and fall time specs see (Δt/ΔV) in Recommended Operating Conditions.
  - Specified High and low levels. See (V<sub>IH</sub> and V<sub>II</sub>) in Recommended Operating Conditions.
- 2. Recommend output conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part
  - Outputs should not be pulled above V<sub>CC</sub>



# Typical Application (continued)

#### 10.2.3 Application Curve

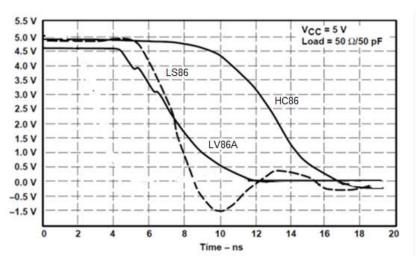


Figure 9. Switching Characteristics Comparison

# **Power Supply Recommendations**

The power supply can be any voltage between the minimum and maximum supply voltage rating located in Recommended Operating Conditions.

Each V<sub>CC</sub> terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends 0.1  $\mu$ F and if there are multiple  $V_{CC}$  terminals then .01 or .022  $\mu$ F is recommended for each power terminal. It is okay to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1 µF and 1 µF are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

#### 12 Layout

#### 12.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V<sub>CC</sub> whichever make more sense or is more convenient. It is generally okay to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the IOs so they also cannot float when disabled.

#### 12.2 Layout Example

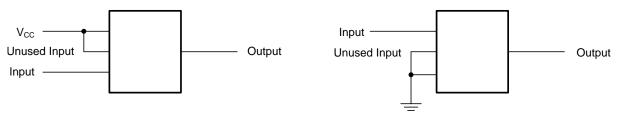


Figure 10. Layout Recommendation



# 13 Device and Documentation Support

#### 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY	
SN54LV86A	Click here	Click here	Click here	Click here	Click here	
SN74LV86A	Click here	Click here	Click here	Click here	Click here	

#### 13.2 Trademarks

All trademarks are the property of their respective owners.

## 13.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

#### 13.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

# 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)			, ,	
SN74LV86AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86ADGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV86A	Samples
SN74LV86APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples
SN74LV86APWT	ACTIVE	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV86A	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

# PACKAGE OPTION ADDENDUM

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN74LV86A:

Automotive: SN74LV86A-Q1

■ Enhanced Product : SN74LV86A-EP

#### NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV86ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV86ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV86ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV86ANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV86APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV86APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV86ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LV86ADGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74LV86ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LV86ANSR	SO	NS	14	2000	356.0	356.0	35.0
SN74LV86APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV86APWT	TSSOP	PW	14	250	356.0	356.0	35.0

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LV86AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LV86APW	PW	TSSOP	14	90	530	10.2	3600	3.5

# DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
  - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# DB (R-PDSO-G\*\*)

# PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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